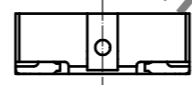
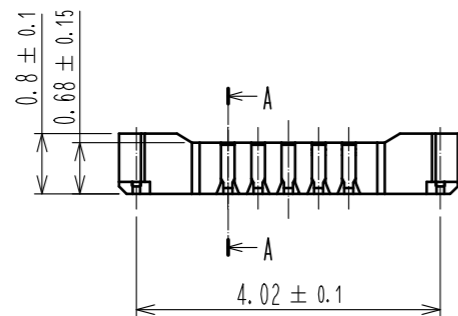
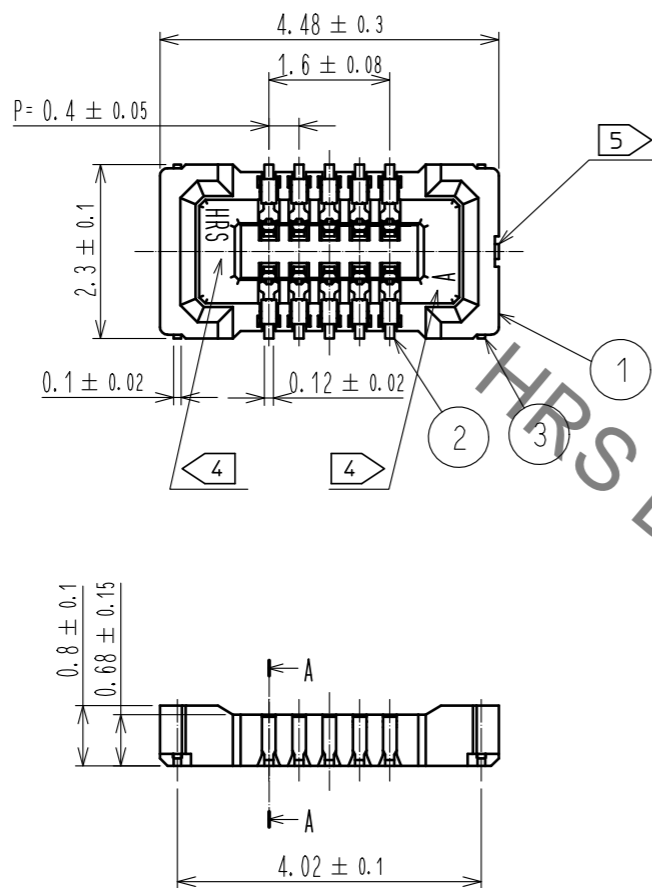
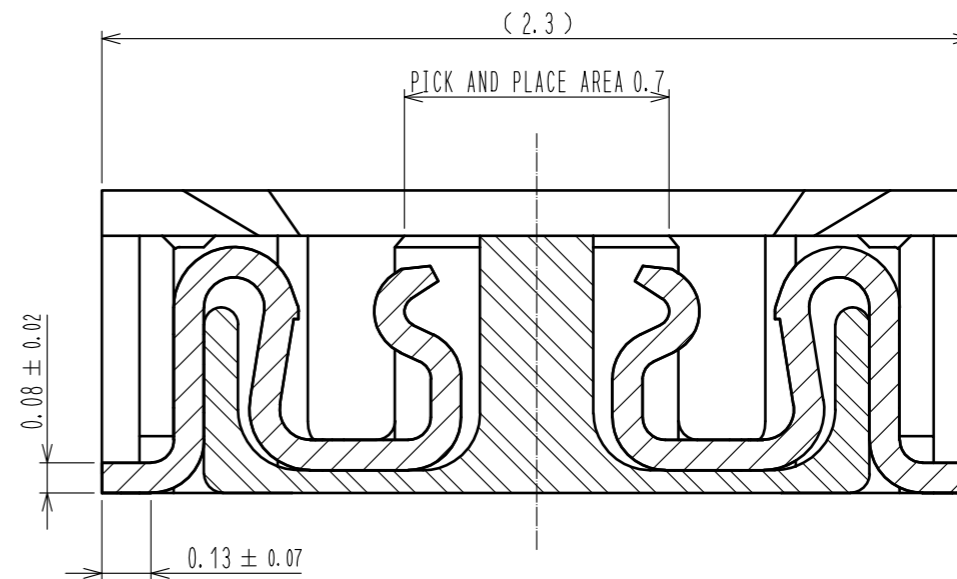


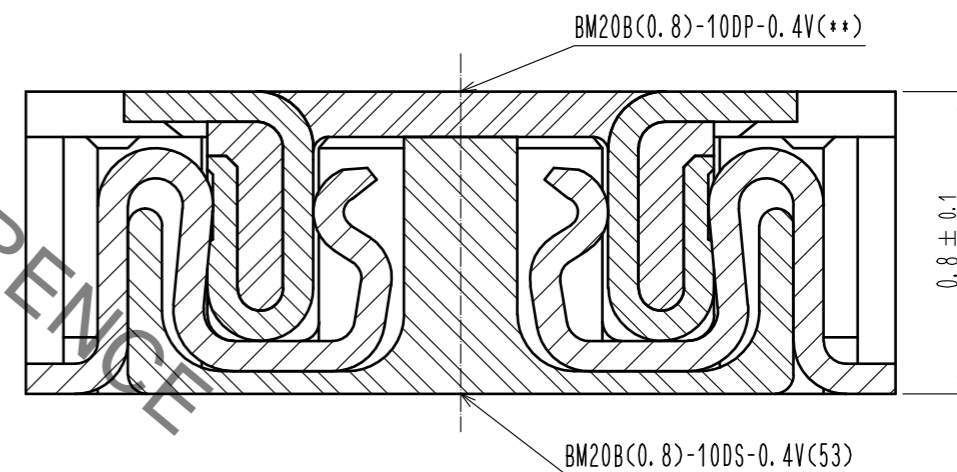
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A-A(50:1)



ENGAGEMENT FIGURE (50:1)

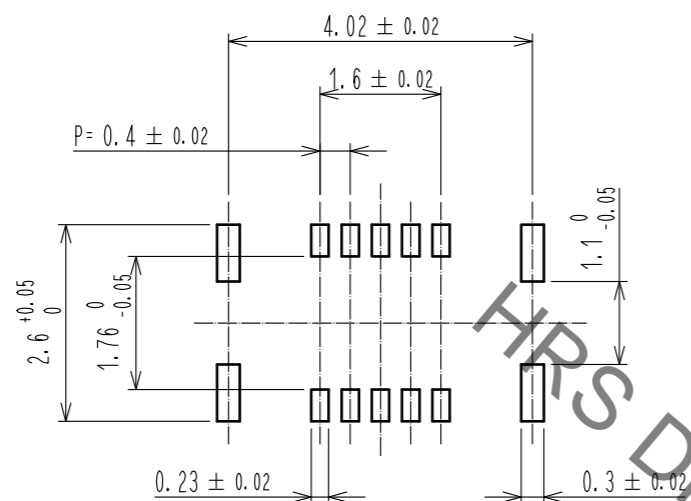


- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
 - 2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μm MIN
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
 - 5. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

4	PS	CLEAR (EMBOSSED CARRIER TAPE)						
3	BRASS	3	7	PS	CLEAR (REINFORCEMENT COLLAR)			
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS			
UNITS	mm	SCALE	10:1	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : MO. ISHIDA	15.10.17	DRAWING NO. EDC-332314-53-01				
		CHECKED : TS. MIYAZAKI	15.10.17	PART NO. BM20B(0.8)-10DS-0.4V(53)				
		DESIGNED : RT. SHIMIZU	15.10.16	CODE NO. CL684-9008-4-53				
		DRAWN : KR. AJITO	15.10.16					

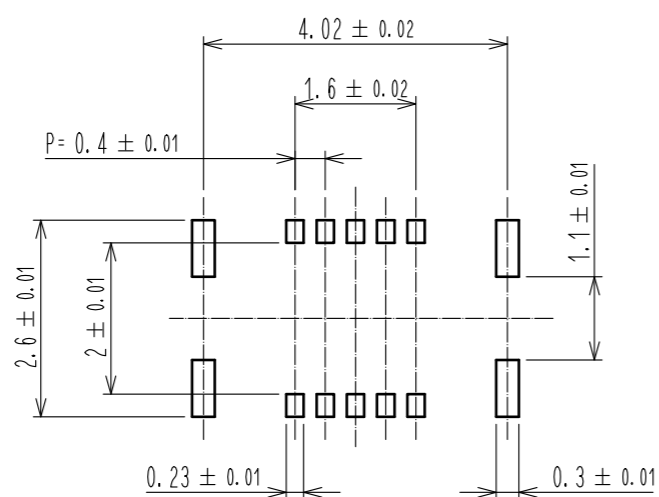
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◆ RECOMMENDED PCB LAYOUT

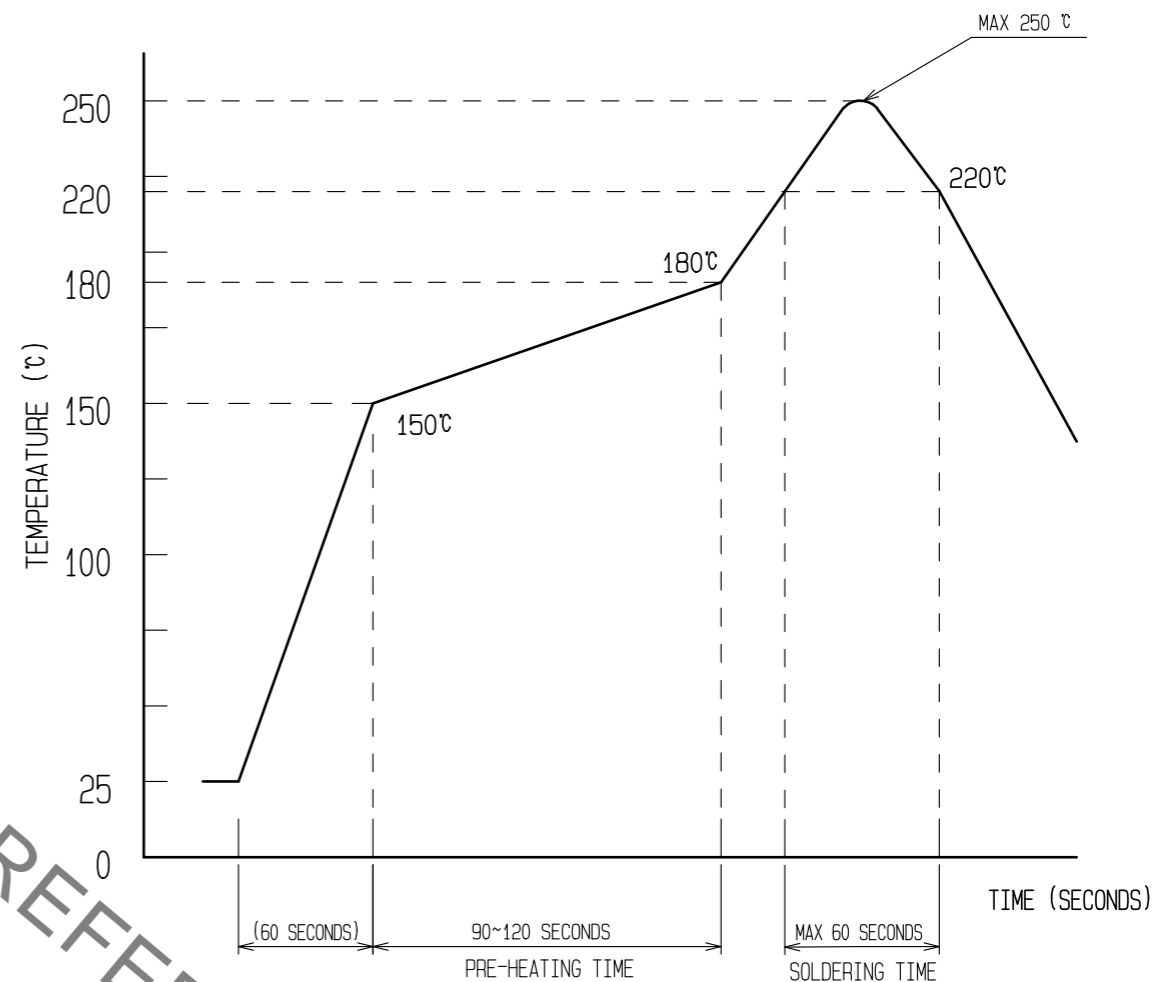


◆ RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : 100 μm



⑥ RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD : IR REFLOW
 NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
- 1) REFLOW TIME
 DURATION ABOVE 220°C, 60 SEC MAX.
 (PEAK TEMPERATURE : 250°C MAX)
 - 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 SEC.

⑥ THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
 ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
 OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
 A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
 PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS	DRAWING NO.	EDC-332314-53-01
	PART NO.	BM20B(0.8)-10DS-0.4V(53)
	CODE NO.	CL684-9008-4-53

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